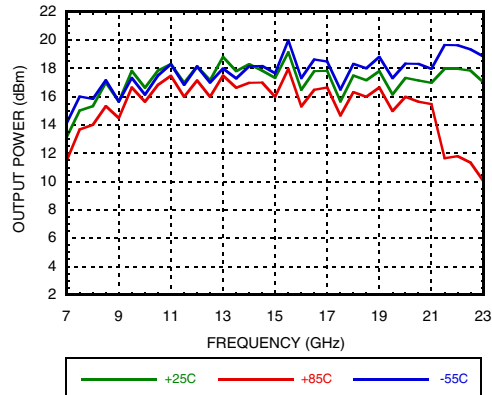
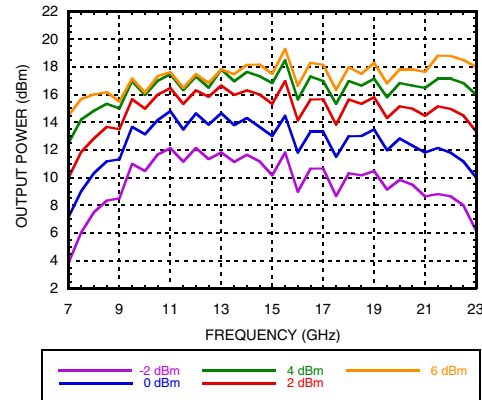


**GaAs MMIC x2 ACTIVE FREQUENCY
MULTIPLIER, 8 - 21 GHz OUTPUT**

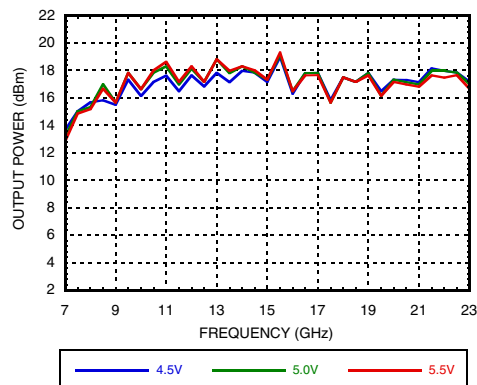
**Output Power vs.
Temperature @ 5 dBm Drive Level**



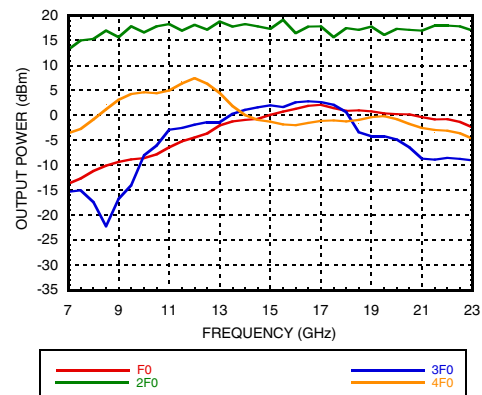
Output Power vs. Drive Level



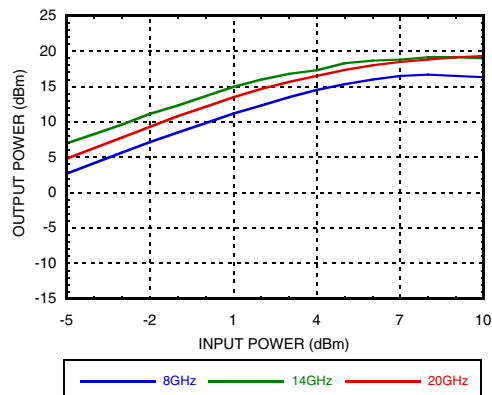
**Output Power vs.
Supply Voltage @ 5 dBm Drive Level**



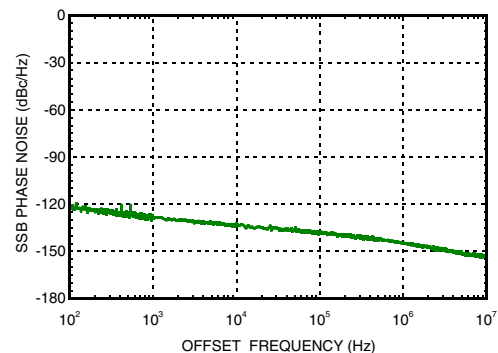
Isolation @ 5 dBm Drive Level



Output Power vs. Input Power

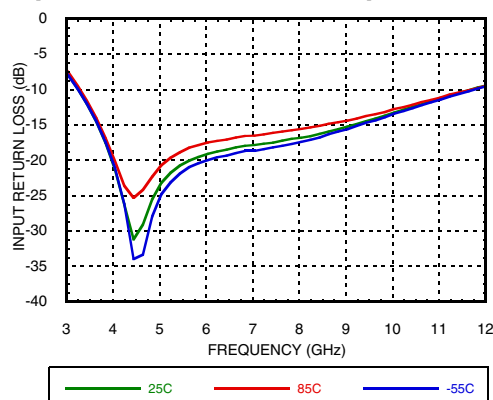


**SSB Phase Noise Performance,
Fout = 16 GHz, Input Power = +3 dBm**

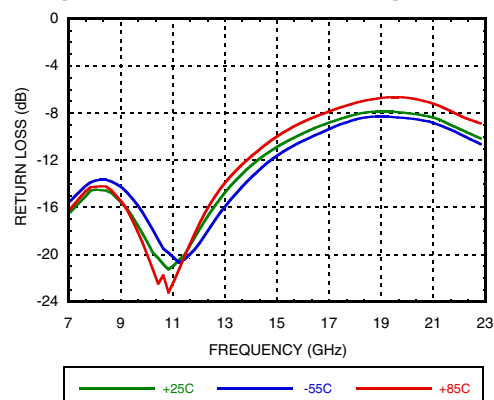


**GaAs MMIC x2 ACTIVE FREQUENCY
MULTIPLIER, 8 - 21 GHz OUTPUT**

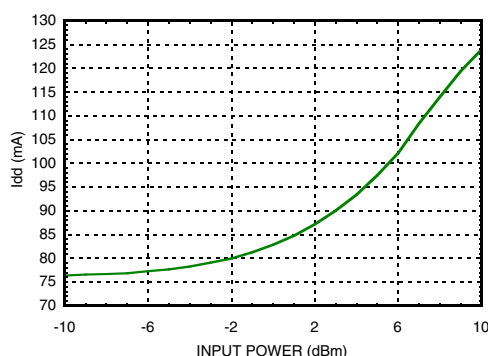
Input Return Loss vs. Temperature



Output Return Loss vs. Temperature



Supply Current vs. Input Power



Absolute Maximum Ratings

RF Input ($V_{dd1} = V_{dd2} = +5V$)	+10 dBm
Supply Voltage (V_{dd1}, V_{dd2})	+5.5 Vdc
Channel Temperature	175 °C
Continuous P_{diss} ($T = 85$ °C) (derate 10.4 mW/°C above 85 °C)	940 mW
Thermal Resistance (channel to die bottom)	95.9 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-55 to +85 °C

Typical Supply Current vs. V_{dd1}, V_{dd2}

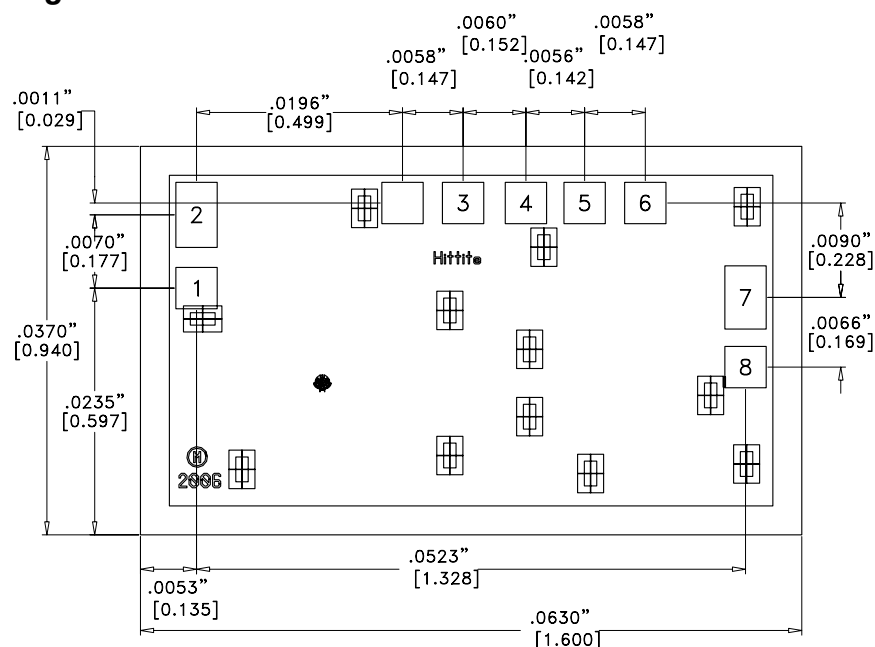
V_{dd1}, V_{dd2} (Vdc)	$I_{dd1} + I_{dd2}$ (mA)
4.5	97
5.0	98
5.5	99



**ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS**

**GaAs MMIC x2 ACTIVE FREQUENCY
MULTIPLIER, 8 - 21 GHz OUTPUT**

Outline Drawing



Die Packaging Information ^[1]

Standard	Alternate ^[2]
GP-2 (Gel Pack)	—

[1] Refer to the "Packaging Information" section for die packaging dimensions.

[2] Reference this suffix only when ordering alternate die packaging.

NOTES:

1. ALL DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. DIE THICKNESS IS .004"
3. TYPICAL BOND PAD IS .004" SQUARE.
4. TYPICAL BOND SPACING IS .006" CENTER TO CENTER.
5. BOND PAD METALIZATION: GOLD
6. BACKSIDE METALIZATION: GOLD
7. BACKSIDE METAL IS GROUND.
8. NO CONNECTION REQUIRED FOR UNLABELED BOND PADS.

Pad Descriptions

Pad Number	Function	Description	Interface Schematic
1, 4, 8	GND	Die bottom must be connected to RF ground.	
2	RFIN	This pad is AC coupled and matched to 50 Ohms.	
3	Vgg	Gate control for multiplier. Adjust to achieve I _{dd} of 98 mA. Please follow "MMIC Amplifier Biasing Procedure" Application note.	
5, 6	Vdd1, Vdd2	Supply voltage 5V ± 0.5V.	
7	RFOUT	This pad is AC coupled and matched to 50 Ohms.	

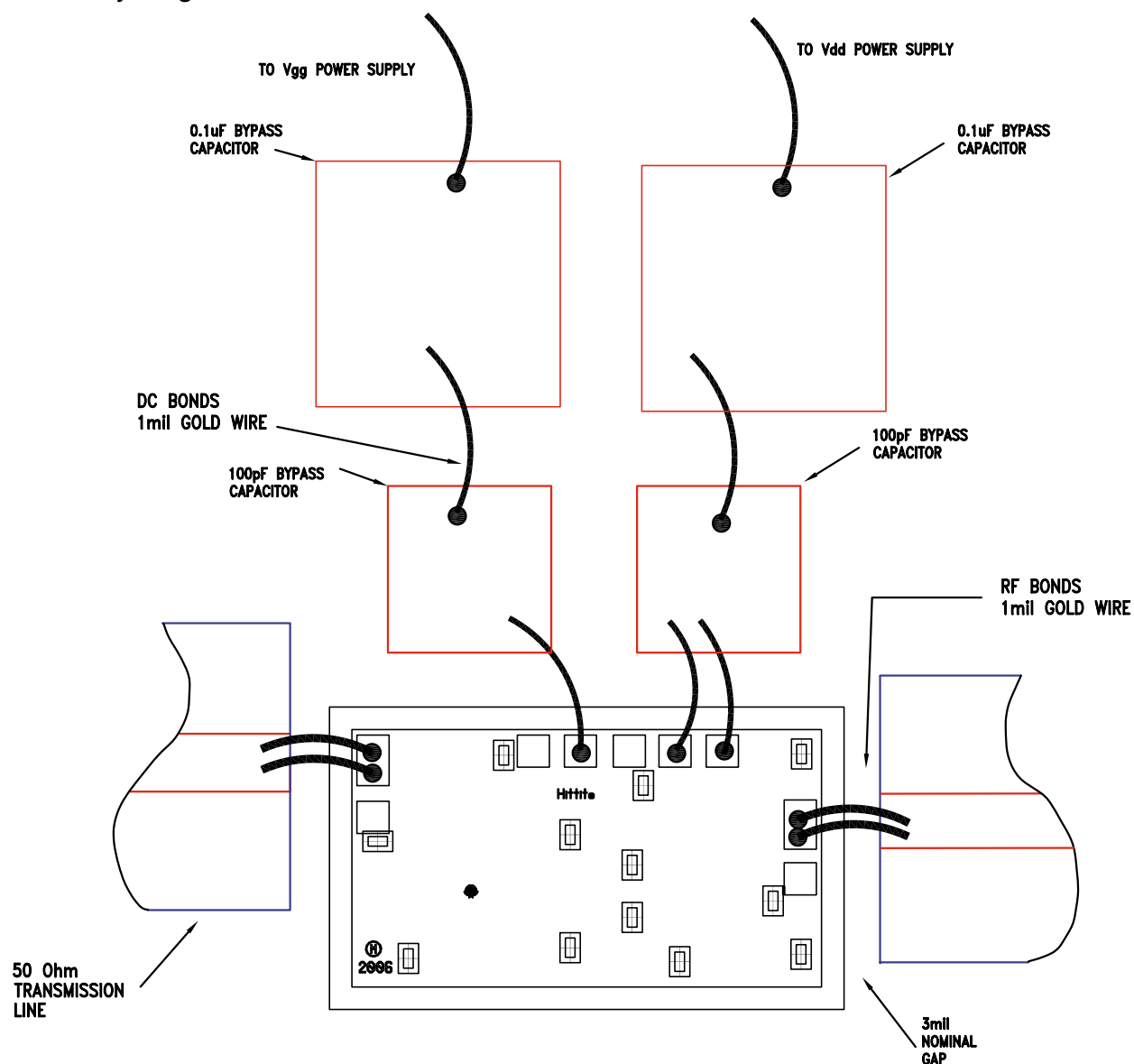
For price, delivery and to place orders: Analog Devices, Inc., 2 Elizabeth Drive, Chelmsford, MA 01824

Phone: 978-250-3343 Fax: 978-250-3373 Order On-line at www.hittite.com

Application Support: Phone: 978-250-3343 or apps@hittite.com

**GaAs MMIC x2 ACTIVE FREQUENCY
MULTIPLIER, 8 - 21 GHz OUTPUT**

Assembly Diagram



GaAs MMIC x2 ACTIVE FREQUENCY MULTIPLIER, 8 - 21 GHz OUTPUT

Mounting & Bonding Techniques for Millimeterwave GaAs MMICs

The die should be attached directly to the ground plane eutectically or with conductive epoxy (see HMC general Handling, Mounting, Bonding Note).

50 Ohm Microstrip transmission lines on 0.127mm (5 mil) thick alumina thin film substrates are recommended for bringing RF to and from the chip (Figure 1). If 0.254mm (10 mil) thick alumina thin film substrates must be used, the die should be raised 0.150mm (6 mils) so that the surface of the die is coplanar with the surface of the substrate. One way to accomplish this is to attach the 0.102mm (4 mil) thick die to a 0.150mm (6 mil) thick molybdenum heat spreader (moly-tab) which is then attached to the ground plane (Figure 2).

Microstrip substrates should be located as close to the die as possible in order to minimize bond wire length. Typical die-to-substrate spacing is 0.076mm to 0.152 mm (3 to 6 mils).

Handling Precautions

Follow these precautions to avoid permanent damage.

Storage: All bare die are placed in either Waffle or Gel based ESD protective containers, and then sealed in an ESD protective bag for shipment. Once the sealed ESD protective bag has been opened, all die should be stored in a dry nitrogen environment.

Cleanliness: Handle the chips in a clean environment. DO NOT attempt to clean the chip using liquid cleaning systems.

Static Sensitivity: Follow ESD precautions to protect against ESD strikes.

Transients: Suppress instrument and bias supply transients while bias is applied. Use shielded signal and bias cables to minimize inductive pick-up.

General Handling: Handle the chip along the edges with a vacuum collet or with a sharp pair of bent tweezers. The surface of the chip may have fragile air bridges and should not be touched with vacuum collet, tweezers, or fingers.

Mounting

The chip is back-metallized and can be die mounted with AuSn eutectic preforms or with electrically conductive epoxy. The mounting surface should be clean and flat.

Eutectic Die Attach: A 80/20 gold tin preform is recommended with a work surface temperature of 255 °C and a tool temperature of 265 °C. When hot 90/10 nitrogen/hydrogen gas is applied, tool tip temperature should be 290 °C. DO NOT expose the chip to a temperature greater than 320 °C for more than 20 seconds. No more than 3 seconds of scrubbing should be required for attachment.

Epoxy Die Attach: Apply a minimum amount of epoxy to the mounting surface so that a thin epoxy fillet is observed around the perimeter of the chip once it is placed into position. Cure epoxy per the manufacturer's schedule.

Wire Bonding

Ball or wedge bond with 0.025mm (1 mil) diameter pure gold wire. Thermosonic wirebonding with a nominal stage temperature of 150 °C and a ball bonding force of 40 to 50 grams or wedge bonding force of 18 to 22 grams is recommended. Use the minimum level of ultrasonic energy to achieve reliable wirebonds. Wirebonds should be started on the chip and terminated on the package or substrate. All bonds should be as short as possible <0.31mm (12 mils).

